

A HIGH DENSITY, ZERO-HEIGHT, FREE FLOATING INTERCONNECT METHOD AND APPARATUS

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ABSTRACT OF THE DISCLOSURE

A method and circuit board assembly provide a zero interconnection height in a board-to-board interconnect while maintaining efficient space allocation for multiple axis connections by providing a floating connection in one plane thereby enabling a connection in another plane. A method for interconnecting includes aligning a first circuit board having a first plurality of through-holes with a second circuit board having a second plurality of through-holes by matching the first plurality of through-holes with the second plurality of through-holes, the aligning providing an interconnection height of zero between the first circuit board and the second circuit board, aligning at least one pass-through socket with the aligned combination of the first circuit board and second circuit board, the at least one pass-through socket including pass-through socket through-holes, and inserting one or more pins disposed on a pin header through the at least one pass-through socket, the first circuit board and the second circuit board. The method further includes floating one of the first circuit board and the second circuit board prior to inserting the pin header, the floating enabling the first circuit board to interconnect with the second circuit board with a connector aligned along an axis different from the pin header.